Variant: 001
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TID #: TIDA-01002

TIDA-01002 REV E3 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		TIDA-01002	Any	Printed Circuit Board	
2	C2, C6, C9, C36	4	0.1µF	C1005X7R1E104K050BB	TDK Corporation	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0402	0402 (1005 Metric)
3	C3, C12, C35	3	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0402	0402
4	C4, C19, C23, C25, C27, C28, C37	7	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402	0402
5	C5, C8, C11, C30	4	10uF	GRM21BR71A106KE51L	MuRata	CAP, CERM, 10uF, 10V, +/-10%, X7R, 0805	0805
6	C7, C10, C13, C16, C20, C24, C26, C29	8	0.01uF	GRM155R71C103KA01D	MuRata	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0402	0402
7	C14	1	4.7uF	JMK107BB7475MA-T	Taiyo Yuden	CAP, CERM, 4.7 µF, 6.3 V, +/- 10%, X7R, 0603	0603
8	C15	1	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0402	0402
9	C17, C21	2	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, C0G/NP0, 0402	0402
10	C18, C22	2	4.7µF	CL10B475KQ8NQNC	Samsung Electro-Mechanics America, Inc	CAP CER 4.7UF 6.3V 10% X7R 0603	0603 (1608 Metric)
11	C31, C32	2	10uF	CL21B106KOQNNNE	Samsung Electro-Mechanics	CAP, CERM, 10 µF, 16 V, +/- 10%, X7R, 0805	0805
12	C33	1	10uF	GRM21BR71A106KE51L	MuRata	CAP, CERM, 10 µF, 10 V, +/- 10%, X7R, 0805	0805
13	C34	1	4.7uF	GRM188Z71C475KE21D	MuRata	CAP, CERM, 4.7 µF, 16 V,+/- 10%, X7R, 0603	0603
14	J1	1		59S10H-40ML5-Z	Rosenberger	Connector, HF, 50 Ohm, TH	SMA Connector
15	L1, L2, L7, L8, L9	5	1000 ohm	BLM15AX102SN1D	MuRata	Ferrite Bead, 1000 ohm @ 100 MHz, 0.35 A, 0402	0402
16	L3	1	4.7uH	CBC3225T4R7MR	Taiyo Yuden	Inductor, Wirewound, 4.7 µH, 1.01 A, 0.1 ohm, SMD	3.2x2.5x2.5mm
17	L4	1	100uH	CBC3225T101MR	Taiyo Yuden	Inductor, Wirewound, 100 µH, 0.27 A, 1.4 ohm, SMD	3.2x2.5x2.5mm
18	L10	1	10uH	74479887310A	Wurth Elektronik	Inductor, Shielded Drum Core, Metal Composite, 10 µH, 0.125 A, 0.3 ohm, SMD	2.5x1x2mm
19	L11	1	2.2uH	74479775222	Wurth Elektronik	Inductor, Shielded Drum Core, Metal Composite, 2.2 µH, 0.5 A, 0.23 ohm, SMD	2x1.2x1mm
20	R1, R2	2	2.00k	CRCW04022K00FKED	Vishay-Dale	RES, 2.00 k, 1%, 0.063 W, 0402	0402
21	R3, R6, R20	3	10k	CRCW040210K0JNED	Vishay-Dale	RES, 10 k, 5%, 0.063 W, 0402	0402
22	R4, R5, R7, R8	4	3.3k	CRCW04023K30JNED	Vishay-Dale	RES, 3.3 k, 5%, 0.063 W, 0402	0402
23	R9, R11, R17	3	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
24	R12	1	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9 ohm, 1%, 0.063W, 0402	0402
25	R13	1	33	CRCW040233R0JNED	Vishay-Dale	RES, 33 ohm, 5%, 0.063W, 0402	0402
26	R15, R16	2	10k	CRCW040210K0JNED	Vishay-Dale	RES, 10k ohm, 5%, 0.063W, 0402	0402
27	R18	1	4.70k	CRG0402F4K7	TE Connectivity	RES, 4.70 k, 1%, 0.063 W, 0402	0402
28	R21, R25	2	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
29	R22	1	82.5k	CRCW040282K5FKED	Vishay-Dale	RES, 82.5 k, 1%, 0.063 W, 0402	0402
30	R23	1	33.2k	CRCW040233K2FKED	Vishay-Dale	RES, 33.2 k, 1%, 0.063 W, 0402	0402
31	U1	1		DS90UB913ATRTVTQ1	Texas Instruments	DS90UB913A-Q1/DS90UB914A-Q1 25 to 100 MHz 10/20-Bit FPD-Link III Serializer and Deserializer, RTV0032A	RTV0032A
32	U2	1		AS0140	ON Semiconductor	1MP+ISP Single Package Solution, BGA130	BGA, 8.5x8.5mm, 130 Balls
33	U3	1		TPS62170QDSGRQ1	Texas Instruments	3-V to17-V 0.5-A Step-Down Converters with DCS-Control™, DSG0008A	DSG0008A
34	U4	1		TPS62171QDSGRQ1	Texas Instruments	3-V to 17-V, 0.5-A Step-Down Converter with DCS-Control, DSG0008A	DSG0008A
35	Y1	1		ASDMB-48.000MHZ-LY-T	Abracon Corporation	OSC, 48MHz, 1.8 to 3.3V, SMD	2.5x2mm
36	FID1, FID2, FID3, FID4, FID5, FID6	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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